

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Currently Amended) A temperature control system for a semiconductor processing facility comprising:

a cooling unit for controlling the temperature of a cooling fluid wherein said cooling unit is a refrigeration unit that provides compressed refrigerant; and

a plurality of remote temperature control modules in fluid communication with said cooling unit, each of said remote temperature control modules including[[:]]:

a cooling fluid circulation loop for circulating said cooling fluid through said remote temperature control module, said cooling fluid circulation loop being in fluid communication with said cooling unit;

a heat transfer fluid circulation loop for circulating a heat transfer fluid through said remote temperature control module, said heat transfer fluid being in fluid

communication with ^{at least one} process component of said semiconductor processing facility;

~~means for an integrated heat exchanger including a portion of the cooling fluid~~
circulation loop, a portion of the heat transfer fluid circulation loop and ^{an electrical} ~~a~~ heat source, the integrated heat exchanger exchanging heat between said cooling fluid that is circulated in said cooling fluid circulation loop and said heat transfer fluid that is circulated in said heat transfer fluid circulation loop, ^{insert B,}

a cooling fluid control valve in fluid communication with said cooling fluid circulation loop for controlling the circulation of said cooling fluid through said cooling fluid circulation loop; and

b ~~a controller programmed with~~ temperature control logic for controlling said cooling fluid control valve ~~in~~ ^{and}
b ~~controlling said current controller~~
~~response to temperature set point information and temperature feedback information~~
related to said process component.

2. (Original) The temperature control system of claim 1 wherein each of said remote temperature control modules includes a heat source in thermal communication with said heat transfer fluid for providing heat to said heat transfer fluid.

3. (Original) The temperature control system of claim 2 wherein said heat source is controlled by said temperature control logic in response to said temperature set point information and temperature feedback information related to said process component.

4. (Original) ~~The temperature control system of claim 3 wherein said heat source is integrated with said means for exchanging heat.~~

5. (Original) ~~The temperature control system of claim 4 wherein said means for exchanging heat includes a heat exchanger that integrates a portion of said cooling fluid circulation loop, a portion of said heat transfer fluid circulation loop, and said heat source.~~

4
6. (Original) The temperature control system of claim 1 wherein said cooling unit is physically separate from said plurality of remote temperature control modules.

5
7. (Original) The temperature control system of claim ~~6~~ ⁴ wherein said cooling unit is located in a utility basement of said semiconductor processing facility.

^u
8. (Original) The temperature control system of claim ⁵7 wherein said plurality of remote temperature control modules are located in a subfloor area of said semiconductor processing facility.

⁷
9. (Original) The temperature control system of claim ⁵7 wherein said plurality of remote temperature control modules are physically connected to process tools within said semiconductor processing facility.

⁸
b 10. (Currently Amended) The temperature control system of claim 1 wherein ^{insert B2} said cooling unit is set to maintain said cooling fluid at a temperature ~~that is related to the where the~~ ^{correlating} ~~temperature correlates to a lowest set point~~ ^{at least one} temperature among all of said process components that are thermally influenced by said cooling fluid.

⁹
11. (Currently Amended) The temperature control system of claim 1 wherein said cooling unit ~~is a refrigeration unit that~~ provides the compressed refrigerant to said plurality of remote temperature control modules.

¹⁰
12. (Original) The temperature control system of claim ⁹11 wherein:

said cooling fluid circulation loop is a refrigerant circulation loop for circulating refrigerant through said remote temperature control module;

said cooling fluid control valve is a thermal expansion valve for controlling the circulation of said refrigerant through said refrigerant circulation loop; and

further including a flow control valve for controlling the circulation of said refrigerant through said refrigerant circulation loop, said flow control valve being downstream from said thermal expansion valve.

¹¹
~~13~~. (Original) The temperature control valve of claim ¹⁰~~12~~ wherein each of said remote temperature control modules includes a heat source in thermal communication with said heat transfer fluid for providing heat to said heat transfer fluid.

¹²
~~14~~. (Currently Amended) A temperature control system for a process component of a semiconductor processing facility comprising:

b ^{at least one}
¹ remote temperature control module, said remote temperature control module including[[:]]:

a cooling fluid input for receiving cooling fluid from a cooling unit that serves multiple remote temperature control modules where said cooling fluid input is a refrigerant input for receiving compressed refrigerant from a refrigeration unit;

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a cooling fluid output for returning cooling fluid to said cooling unit that serves multiple remote temperature control modules;

a cooling fluid circulation loop for circulating said cooling fluid through said remote temperature control module;

a heat transfer fluid input for receiving heat transfer fluid from said process component;

a heat transfer fluid output for returning said heat transfer fluid to said process component;

a heat transfer fluid circulation loop for circulating said heat transfer fluid through said remote temperature control module, said heat transfer fluid being in fluid communication with said process component of said semiconductor processing facility;

~~means for exchanging~~ an integrated heat exchanger including a portion of the cooling fluid circulation loop, a portion of the heat transfer fluid circulation loop and a

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b *an electrical*

1 heat source, the integrated heat exchanger exchanging heat between said cooling fluid

that is circulated in said cooling fluid circulation loop and said heat transfer fluid that is

circulated in said heat transfer fluid circulation loop

insert B3

a cooling fluid control valve in fluid communication with said cooling fluid

circulation loop for controlling the circulation of said cooling fluid through said cooling

fluid circulation loop; and

a controller programmed with a

temperature control logic for controlling said cooling fluid control valve *and*

controlling said current controller

~~response to temperature set point information and temperature feedback information~~

~~related to said process component.~~

13
15.

(Original) The temperature control system of claim *12* ~~14~~ wherein said remote temperature

the
control module includes a heat source in thermal communication with said heat transfer fluid for providing heat to said heat transfer fluid.

14
16.

(Currently Amended) The temperature control system of claim *13* ~~15~~ wherein said heat source is controlled by said temperature control logic in response to [[said]] temperature set point information and [[said]] temperature feedback information related to said process component.

17.

~~(Original) The temperature control system of claim 16 wherein said heat source is integrated with said means for exchanging heat.~~

18. (Original) The temperature control system of claim 17 wherein said means for exchanging heat includes a heat exchanger that integrates a portion of said cooling fluid circulation loop, a portion of said heat transfer fluid circulation loop, and said heat source.

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¹⁵
~~19~~. (Currently Amended) The temperature control system of claim ¹²~~14~~ wherein said cooling unit is physically separate from said remote temperature control module and said multiple remote temperature control modules.

¹⁸
~~20~~. (Original) The temperature control system of claim ¹²~~14~~ wherein said cooling unit is located in a utility basement of said semiconductor processing facility.

¹⁶
~~21~~. (Original) The temperature control system of claim ¹⁵~~19~~ wherein said remote temperature control module is located in a subfloor area of said semiconductor processing facility.

¹⁷
~~22~~. (Original) The temperature control system of claim ¹⁵~~19~~ wherein said remote temperature control module is physically connected to a process tool within said semiconductor processing facility.

¹⁹
~~23~~. (Currently Amended) The temperature control system of claim ¹²~~14~~ wherein said cooling unit is set to maintain said cooling fluid at a temperature ~~related to the where the temperature~~ ^{correlating} ~~correlates to a lowest set point~~ ^{of said at least one} temperature among all remote temperature control modules that are served by said cooling unit.

²⁰
~~24~~. (Currently Amended) The temperature control system of claim ¹²~~14~~ wherein:
~~said cooling fluid input is a refrigerant input for receiving compressed refrigerant from a~~
~~the~~ refrigeration unit ~~[[that]]~~ serves multiple remote temperature control modules;
said cooling fluid output is a refrigerant output for returning expanded refrigerant to said refrigeration unit that serves multiple remote temperature control modules;
said cooling fluid circulation loop is a refrigerant circulation loop for circulating refrigerant through said remote temperature control modules;

said cooling fluid control valve is a thermal expansion valve for controlling the circulation of said refrigerant through said refrigerant circulation loop; and

further including a flow control valve for controlling the circulation of said refrigerant through said refrigerant circulation loop, said flow control valve being downstream from said thermal expansion valve.

²¹
~~25~~. (Currently Amended) A temperature control system for a process component of a semiconductor processing facility comprising:

b *at least one*
a remote temperature control module, said remote temperature control module including[[:]]:

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a cooling fluid input for receiving cooling fluid from a physically separate cooling unit that serves multiple remote temperature control modules where said cooling fluid input is a refrigerant input for receiving compressed refrigerant from a refrigeration unit;

a cooling fluid output for returning cooling fluid to said cooling unit that serves multiple remote temperature control modules;

a cooling fluid circulation loop for circulating said cooling fluid through said remote temperature control module;

a heat transfer fluid input for receiving heat transfer fluid from said process component;

a heat transfer fluid output for returning said heat transfer fluid to said process component;

a heat transfer fluid circulation loop for circulating said heat transfer fluid through said remote temperature control module, said heat transfer fluid being in fluid communication with said process component of said semiconductor processing facility,

wherein said cooling fluid circulation and said heat transfer fluid circulation loop are separate fluid distribution systems;

b ^{*an electrical*}
~~a~~ heat source in thermal communication with said heat transfer fluid for providing heat to said heat transfer fluid;

[[a]] an integrated heat exchanger for exchanging heat between said cooling fluid that is circulated in said cooling fluid circulation loop and said heat transfer fluid that is circulated in said heat transfer fluid circulation loop where the integrated heat exchanger includes a portion of the cooling fluid circulation loop, a portion of the heat transfer fluid circulation loop and the heat source; ^{*electrical*}, *insert B4*

A2
a cooling fluid control valve in fluid communication with said cooling fluid circulation loop for controlling the circulation of said cooling fluid through said cooling fluid circulation loop; and

b ^{*a controller programmed with*}
b ^{*electrical*}
~~temperature control logic for controlling said cooling fluid control valve and said heat source in response to temperature set point information and temperature feedback information related to said process component.~~

²²
~~26.~~ (Original) The temperature control system of claim ²¹~~25~~ wherein said heat source is integrated with said heat exchanger.

²³
~~27.~~ (Original) The temperature control system of claim ²¹~~25~~ wherein said cooling unit is located in a utility basement of said semiconductor processing facility.

²⁴
~~28.~~ (Original) The temperature control system of claim ²³~~27~~ wherein said remote temperature control module is located in a subfloor area of said semiconductor processing facility.

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²³
~~20~~. (Currently Amended) The temperature control system of claim ²¹~~25~~ wherein said cooling unit is set to maintain said cooling fluid at a temperature ~~related to the where the temperature~~ *correlating* *of said at least one* ~~correlates to a lowest set point temperature among all~~ ¹ remote temperature control modules that are served by said cooling unit.

²⁴
~~30~~. (Currently Amended) The temperature control system of claim ²¹~~25~~ wherein:

said cooling fluid input is a refrigerant input for receiving compressed refrigerant from a refrigeration unit [[that]] serves multiple remote temperature control modules;

said cooling fluid output is a refrigerant output for returning expanded refrigerant to said refrigeration unit that serves multiple remote temperature control modules;

Q2 said cooling fluid circulation loop is a refrigerant circulation loop for circulating refrigerant through said remote temperature control modules;

said cooling fluid control valve is a thermal expansion valve for controlling the circulation of said refrigerant through said refrigerant circulation loop; and

further including a flow control valve for controlling the circulation of said refrigerant through said refrigerant circulation loop, said flow control valve being downstream from said thermal expansion valve.

²⁷
~~31~~. (Currently Amended) A temperature control system for a semiconductor processing facility comprising:

a refrigeration unit for providing a compressed refrigerant; and

a plurality of remote temperature control modules in fluid communication with said refrigeration unit, each of said remote temperature control modules including[[:]]:

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a refrigerant circulation loop for circulating said refrigerant through said remote temperature control module, said refrigerant circulation loop being in fluid communication with said refrigeration unit;

a heat transfer fluid circulation loop for circulating a heat transfer fluid through said remote temperature control module, said heat transfer fluid being in fluid communication with a process component of said semiconductor processing facility;

a thermal expansion valve for controlling the circulation of said refrigerant through said refrigerant circulation loop;

a flow control valve in fluid communication with said refrigerant circulation loop for controlling the circulation of said refrigerant through said refrigerant circulation loop; said flow control valve being downstream from said thermal expansion valve;

[[a]] an integrated heat exchanger for exchanging heat between said refrigerant that is circulated in said cooling fluid circulation loop and said heat transfer fluid that is circulated in said heat transfer fluid circulation loop where the integrated heat exchanger includes a portion of the cooling fluid circulation loop, a portion of the heat transfer fluid circulation loop and the heat source and

an electrical, insert B5
a controller programmed with a temperature control logic for controlling said cooling fluid control valve in response to temperature setpoint information and temperature feedback information related to said process component.

28
32.

(Original) The temperature control system of claim 27 wherein each of said remote

temperature control modules includes the a heat source in thermal communication with said heat transfer fluid for providing heat to said heat transfer fluid.

²⁹
~~33.~~

(Currently Amended) A temperature control system for a process component of a

semiconductor processing facility comprising:

b ^{*at least one*}
~~1~~ a remote temperature control module, said remote temperature control module
including[[:]]:

a refrigerant input for receiving compressed refrigerant from a refrigeration unit
that serves multiple remote temperature control modules;

a refrigerant output for returning expanded refrigerant to said refrigeration unit
that serves multiple remote temperature control modules;

A2
a refrigerant circulation loop for circulating said refrigerant through said remote
temperature control module;

a heat transfer fluid input for receiving heat transfer fluid from said process
component;

a heat transfer fluid output for returning said heat transfer fluid to said process
component;

a heat transfer fluid circulation loop for circulating said heat transfer fluid through
said remote temperature control module, said heat transfer fluid being in fluid
communication with said process component of said semiconductor processing facility;

a thermal expansion valve for controlling the circulation of said refrigerant
through said refrigerant circulation loop;

a flow control valve for in fluid communication with said refrigerant circulation
loop controlling the circulation of said refrigerant through said refrigerant circulation
loop, said flow control valve being downstream from said thermal expansion valve;

[[a]] an integrated heat exchanger for exchanging heat between said refrigerant
that is circulated in said refrigerant circulation loop and said heat transfer fluid that is

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circulated in said heat transfer fluid circulation loop where the integrated heat exchanger includes a portion of the cooling fluid circulation loop, a portion of the heat transfer fluid

Q2
b circulation loop and the heat source *an electrical*, *insert B,*
b *a controller programmed with a*
b *temperature control logic for controlling said cooling fluid control valve in*
and controlling said current controller
response to temperature set point information and temperature feedback information
related to said process component.

30
34. (Original) The temperature control system of claim *29* *33* wherein said remote temperature
b control module includes *the electrical* a heat source in thermal communication with said heat transfer fluid for
providing heat to said heat transfer fluid.